

10/582251

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Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	National Phase
Suggested Group Art Unit::	N/A
CD-ROM or CD-R?::	None
Sequence submission?::	None
Computer Readable Form (CRF)?::	No
Title::	METHOD FOR CONSTRUCTING EMI SHIELDING AROUND A COMPONENT EMBEDDED IN A CIRCUIT BOARD
Attorney Docket Number::	0365-0678PUS1
Request for Early Publication?::	No
Request for Non-Publication?::	No
Total Drawing Sheets::	4
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Finland
Status::	Full Capacity
Given Name::	Esa
Family Name::	MUUKKONEN
City of Residence::	Helsinki
Country of Residence::	Finland
Street of mailing address::	Yliskyläntie 6 E 54

City of mailing address:: Helsinki
Country of mailing address:: Finland
Postal or Zip Code of mailing address:: FI-00840

Correspondence Information

Correspondence Customer Number:: 02292

Representative Information

Representative Customer Number:: 02292

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	National Stage of	PCT/FI2004/000752	12/09/04

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
Finland	20031796	12/09/03	Yes

Assignee Information

Assignee name:: Aspocomp Technology Oy
Street of mailing address:: Äyritie 12 a
City of mailing address:: Vantaa
Country of mailing address:: Finland
Postal or Zip Code of mailing address:: FI-01510